**NGUYEN HUU ANH**

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**Brief introduction** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Hi! I’m a software engineer.

I have 5 years of working in the semiconductor industry field as software developer, software designer, technical writer. Hands-on experience in Wire Bonding, C/C++, MFC and C++ Object-Oriented Programming. Experience in compilation, testing and debugging the code using Visual Studio IDE.

I’m looking for a C/C++ software engineer job, willing to relocate.

**Work experience** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**C/C++ Software Developer at Shinkawa Vietnam Co. Ltd** *Nov. 2016 - Oct. 2020*

**Work overview**

* I was responsible for modifying the UI/UX, maintain and develop new features based on design document, making test case and integrated testing software for Wire Bonder, Bump Bonder machine (making chip).
* I also work as a technical writer, analysis and researches customer's requirements, writing function specification, detail specification, manual documents.

**Career project highlight**

* The STRIP MAP function, machine reads the 2D matrix code printed on lead frame by the integrated camera, send this code to HOST and receives corresponding strip map data from HOST. After that, machine executes bonding according to this map data. The format and methods in which strip map information shall be formatted and used to transfer information about a strip map to and from HOST - equipment using the SECS/GEM interface standard. I directly design front-end, implement, testing and writing manual document
* The SIMLOOP function provides a built-in list of loop shape, reduced working time with Automated loop shape optimization and Loop shape editor. Approx. 7% UPH improvements
* CAD Data Making Tool, acts as an AutoCAD 2D 2014, 2015 plug-in, allowing the location of wires on the 2D chip design to be exported to \*.WCD file and then imported into the Wire Bonder machine to reduce working time with wire insert operation. I was responsible for the development and maintenance of this tool after the previous member quit. I’ve made improvements to make it can work on AutoCAD 2D from 2014 to 2020 on both Windows 7/10 64-bit. CAD Data Making Tool developed by HTML, VB.NET, Object ARX and Auto Lisp languages
* I have been trained in Wafer Bump Bonder machine for 2 months *(Oct.2019 – Nov.2019)* at headquarters in Tokyo, Japan. In addition, I worked with 7 engineers and 2 leaders to design and develop software for new machine run on Windows 10 IOT platform

**Personal project**

* I have built a personal web server by using a raspberry pi 3b+ single-board computer. The purpose is to store, selectively share and publish data information. Thinks I used: raspberry pi 3b+, PHP7, HTML, No-IP Dynamic DNS. Link: [*http://nha.sytes.net*](http://nha.sytes.net)

**Skills** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

* Experience in C/C++, MFC, C++ OOP. Having knowledge in Python, PyQT5 design (self-study)
* Basic understanding in embedded systems programming (using STM32F407VG Arm Cortex 32-bit core, FreeRTOS)
* Familiar working with dev tools such Visual Studio, Visual SourceSafe, TFS, Git, STM32CubeMX, Qt Creator, make file, Tera term
* Ability to read and write English technical documents
* Good at problem solving and root cause analysis skills
* Having passion to work

**Education** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**HCMC INDUSTRY AND TRADE COLLEGE** *Sep. 2011 – Jul. 2014*

* *Bachelor of Information Technology*